

GAP-245P-S7-SOLO Series

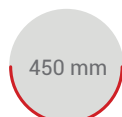
2U RUGGED SERVER



3rd Gen Intel® Xeon® Scalable Processors
Front I/O - Front Power Supply



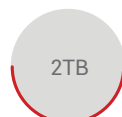
Platform



Depth



CPU



RAM



Hot Swap SSD



I/O Boards

GAP is a family of rugged servers and workstations with an aluminum construction, designed for applications that require robust and qualified MIL-GRADE equipment, suitable for operations in critical environments.

GAP-245P-S7-SOLO rugged servers feature single socket 3rd Gen Intel® Xeon® Scalable Processors (Ice Lake), a balanced architecture that delivers built-in AI acceleration and advanced security capabilities and up to 64 lanes PCI Express Gen 4 per socket to enable higher I/O bandwidth per core. The integrated IPMI services support monitoring, control, and management functions sending alarm notifications in case of critical events.

GAP-245P-S7-SOLO are designed for 19" rackmounting and have a 1U chassis with a depth of 450mm. The layout with front I/O and power supply offers all the I/O ports placed at the front of the chassis as required for "front only" installations.

GAP-245P-S7-SOLO rugged servers feature an internal M.2 NVMe socket and up to two removable U.2 NVMe SSD or up to six removable 2.5" SAS/ SATA SSD. The rugged server can host two Full High Full Length PCIe 4.0 x16 boards and two PCIe 4.0 x8 Low profile boards. Additional boards can be provided with a dedicated retainer kit for an optimal protection against shocks and vibrations also during transport.

GAP servers are designed to meet MIL-STD-810F for temperature and shocks, MIL-STD-167-1A for vibrations. Optionally, they can conform to MIL-STD-461 for EMI /EMC.

The I/O connectors and the power supply input can be provided with MIL-GRADE connectors upon request.

All units are delivered with their inventory list to ensure configuration control and reproducibility over time. Upon request, all server configurations can run specific thermal or mechanical environmental stress test.

FEATURES

- 2U Rugged Server - 450mm depth
- Single Socket Motherboard
- 3rd Gen Intel® Xeon® Scalable Processors
- Front I/O connectors and front Power Input
- Redundant AC or DC Power Supply
- Removable fans
- 2x U.2 NVMe SSD or 3x 2.5" SATA/SAS SSD
- 2x PCIe boards FHFL + 2x PCIe boards LP
- Optional Conformal Coating
- MIL-STD-810G
- Optional MIL-STD-461

Technical Specifications

System

CPU	3 rd Gen Intel® Xeon® Scalable processors Single Socket LGA-4189 (Socket P+) max 205W TDP
Memory	Up to 2TB ECC RDIMM, DDR4-3200MHz; 8 DIMM slots
Chipset	Intel® C621A
Graphics	ASPEED AST2600 BMC
Network Connectivity	1x Dedicated IPMI LAN port 2x 10 GbE ports
Storage	Internal: 1x M.2 NVMe; M-Key, 2280/22110 2x Disk on Module Up to 2x U.2 NVMe or 3x 2.5" SATA / SAS SSD
TPM	1x TPM Header
Motherboard I/O shield	Available on the front: 1x COM; 1x IPMI LAN; 2x USB 2.0; 2x USB 3.2; 2x GbE; 1x VGA
Expansion slots	2x PCI-E 4.0 x16 slot FHFL 2x PCI-E 4.0 x8 slot (Low profile)
Operative Systems	Windows® 10 IoT Enterprise 64bit, Windows® Server 2016 64bit; Windows® Server 2019 64bit; RHEL 8.4 64bit; Ubuntu 20.04.2 LTS SVR 64bit; CentOS 7.9 64bit
IPMI	IPMI2.0, SPM, Watchdog; SNMP and e-mail alarms and notifications
Remote Monitoring	Monitoring, control, and management functions (fan speed, temperature, voltage, redundant power failure, power consumption, disk health, raid health, and memory health)

Power Supply

Power Supply	AC Redundant Power Supply - Optional Single DC Redundant Power Supply - Optional Single
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Mechanical

Dimensions	483 x 88 x 450 mm (W x H x D)
Material	Aluminum with surface passivation treatment
Colour	Black / RAL 9005 - Powder Coating
Mounting	2U 19" rackmount chassis Optional Telescopic slides
Configuration	Front I/O - Front Power Supply
Front Panel Leds / Buttons	Power On/Off button with LED Reset button with LED
Drive Bays	1x 3.5"
Fans	4x removable PWM fans

Environmental - (Design to meet)

Operating Temperatures	0°C to +50°C MIL-STD-810H, Method 501.7 & 502.7 -20°C to +60°C (depending on configuration)
Storage Temperature	-40°C to +70°C MIL-STD-810H, Method 501.7 & 502.7
Humidity	5% – 95% non-condensing MIL-STD-810H 507.6
Operating Vibrations	MIL-STD-167-1A, Type I
Not Operating Vibrations	1.17 Grms, 5-500 Hz MIL-STD-810H, Method 514.8
Operating Shocks	20g / 11ms – half sine MIL-STD-810G, Method 516.7
EMC	Directive 2014/35/UE-LVD Directive 2014/30/UE-EMC Directive 2011/65/UE - RoHS Regulation EC No 1907/2006 MIL-STD-461G (on request)

GAP servers and workstations are designed in accordance with the environmental specifications indicated. Some parameters depend on the configuration. Equipment may be subjected to dedicated test profiles.